



Dear Valued Customer,

The current mechanical specifications for the package can be found at the www.national.com web site or by clicking the following link:

<http://www.national.com/packaging/folders/lda10a.html>

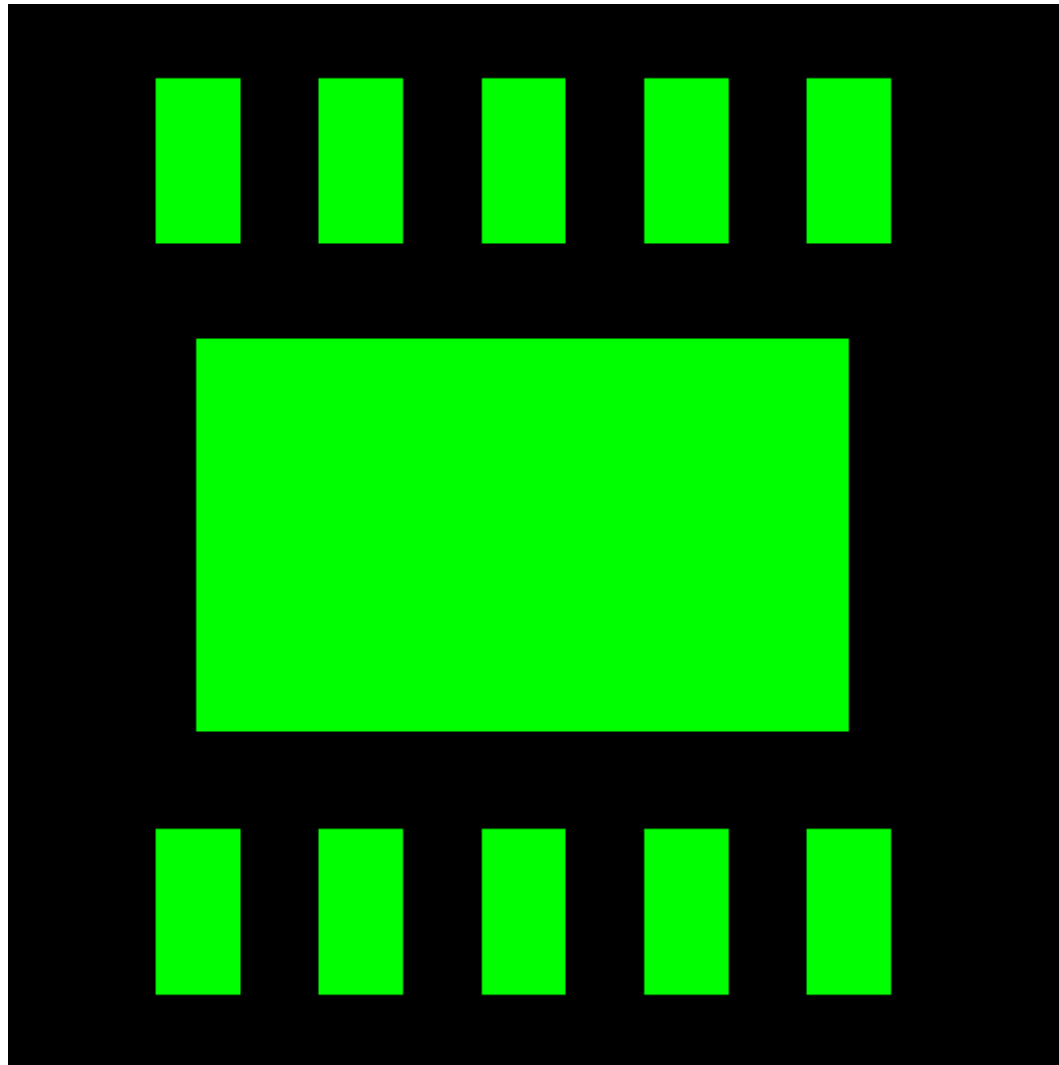
The following pages illustrate the recommended package footprints that apply to this package configuration. They are included in GERBER format for easy incorporation into most PCB layout packages.

For technical support, contact:


<http://www.national.com/support/>

Sincerely yours,

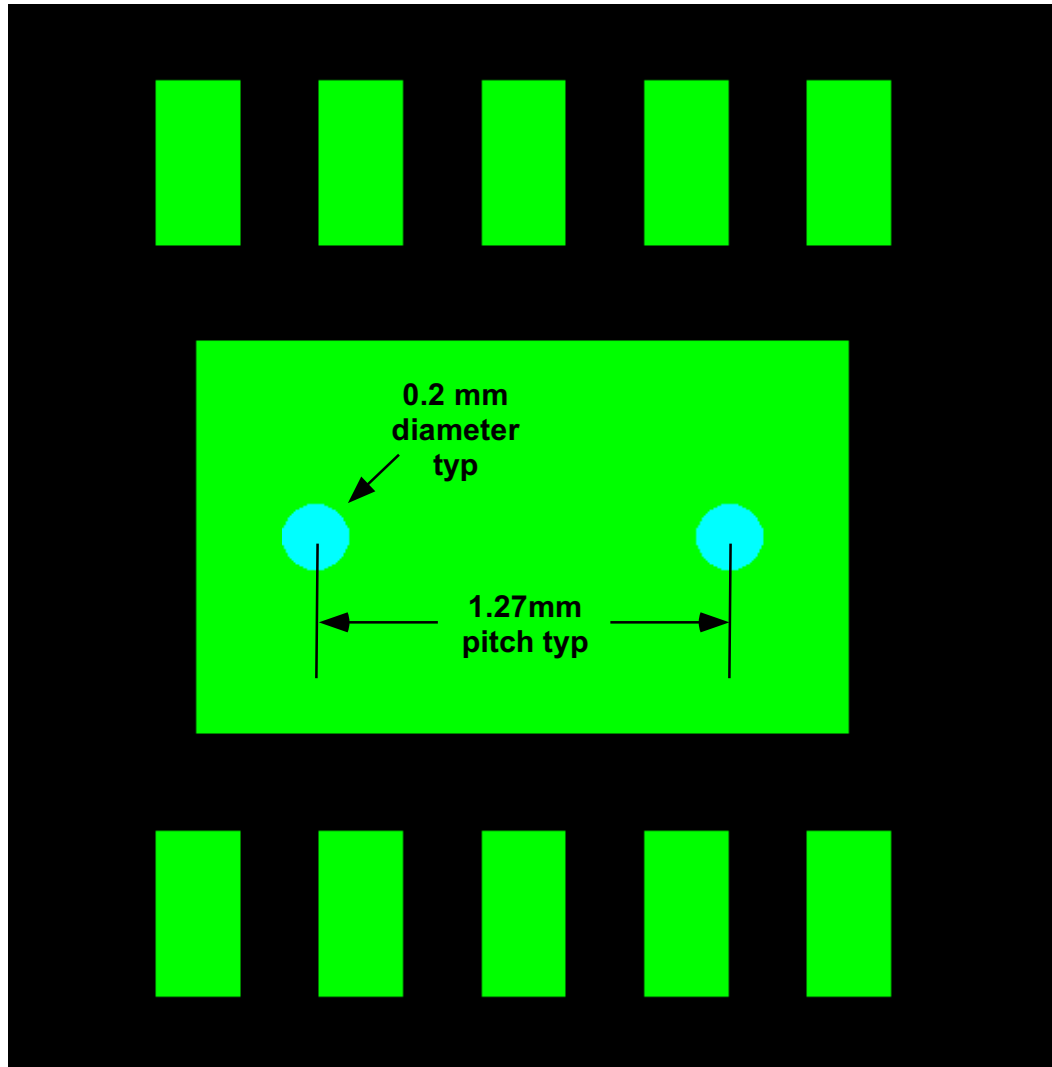
National Semiconductor




TOP ETCH

 = Exposed FR4


 = Exposed metal

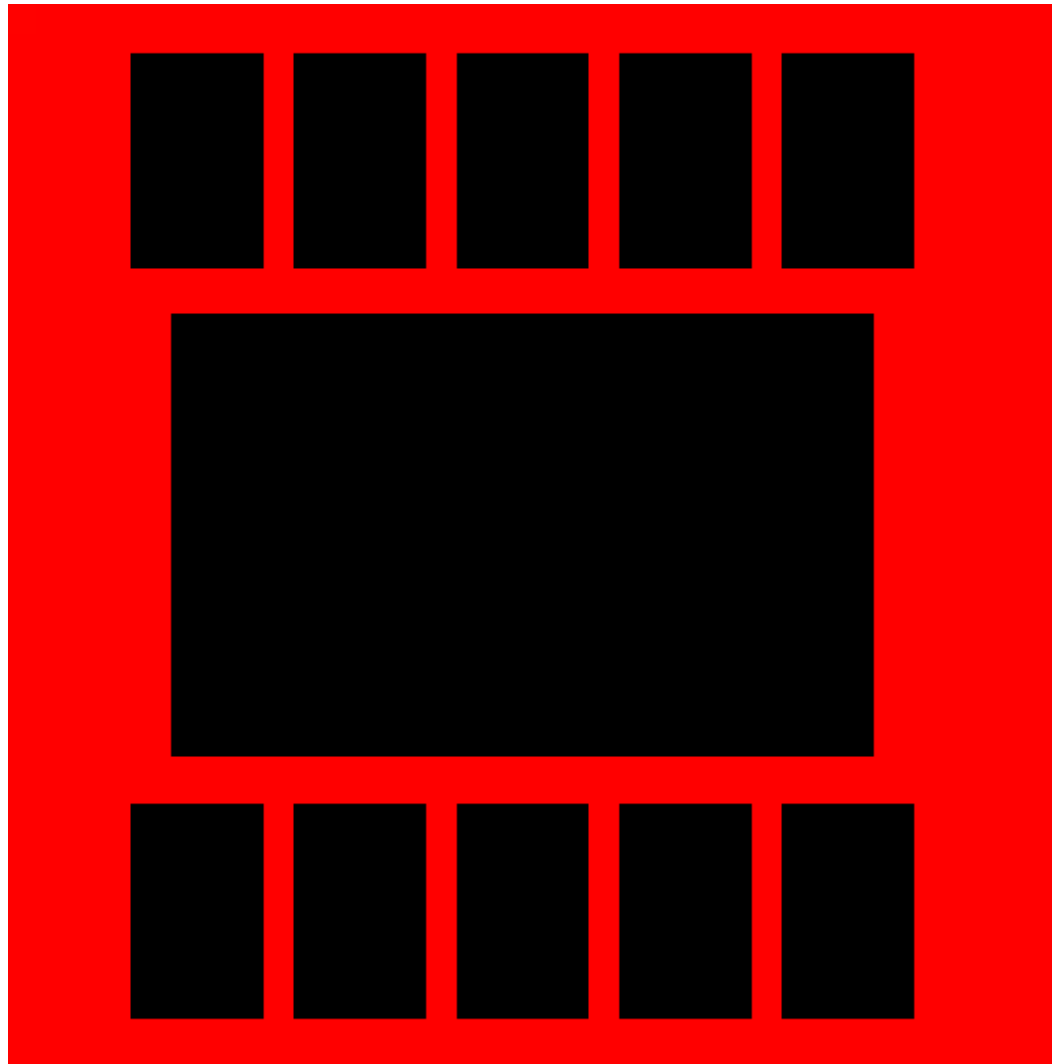


TOP ETCH with THERMAL VIAS


 = Exposed FR4

 = Exposed metal

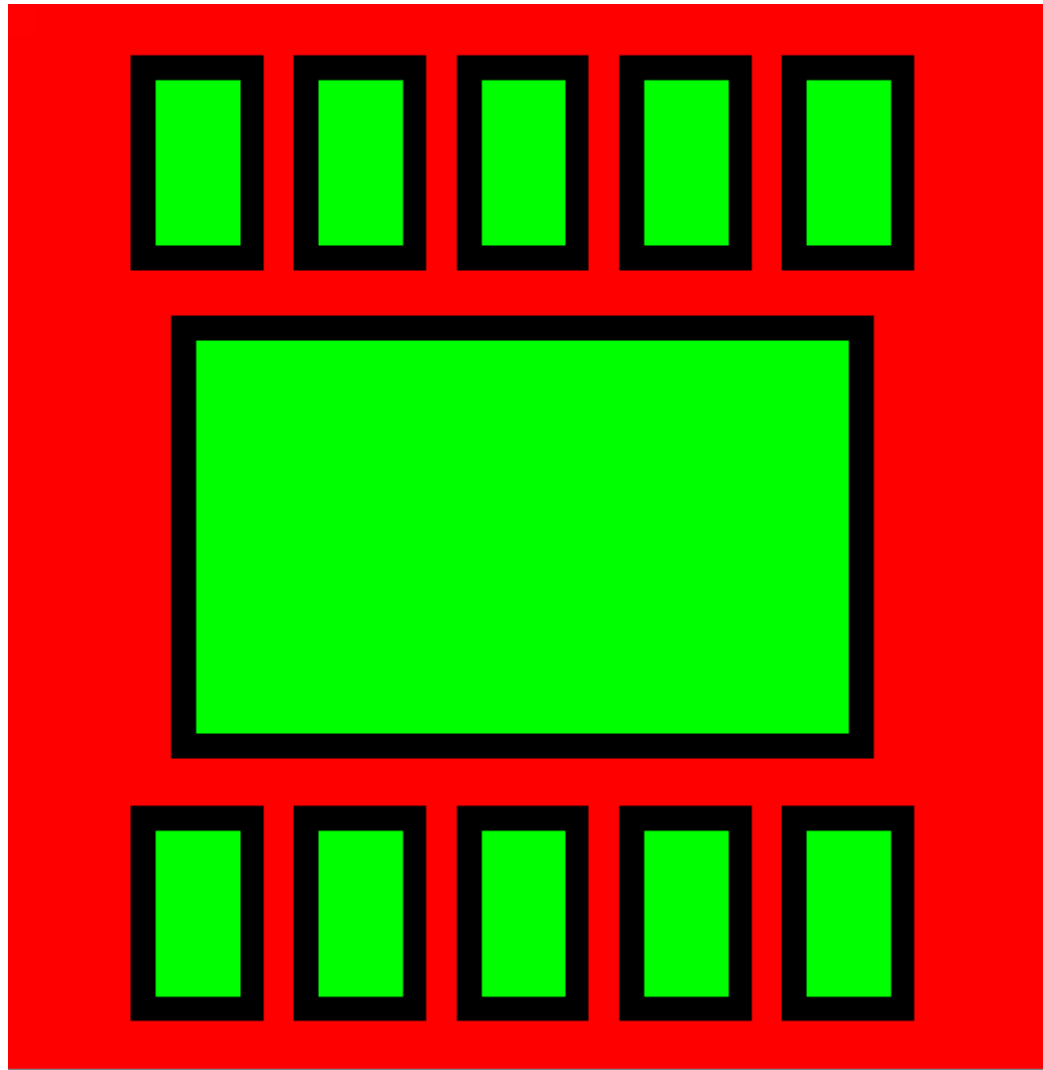
 = Thermal Vias



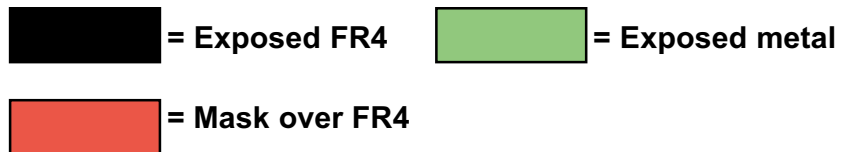
TOP SOLDERMASK

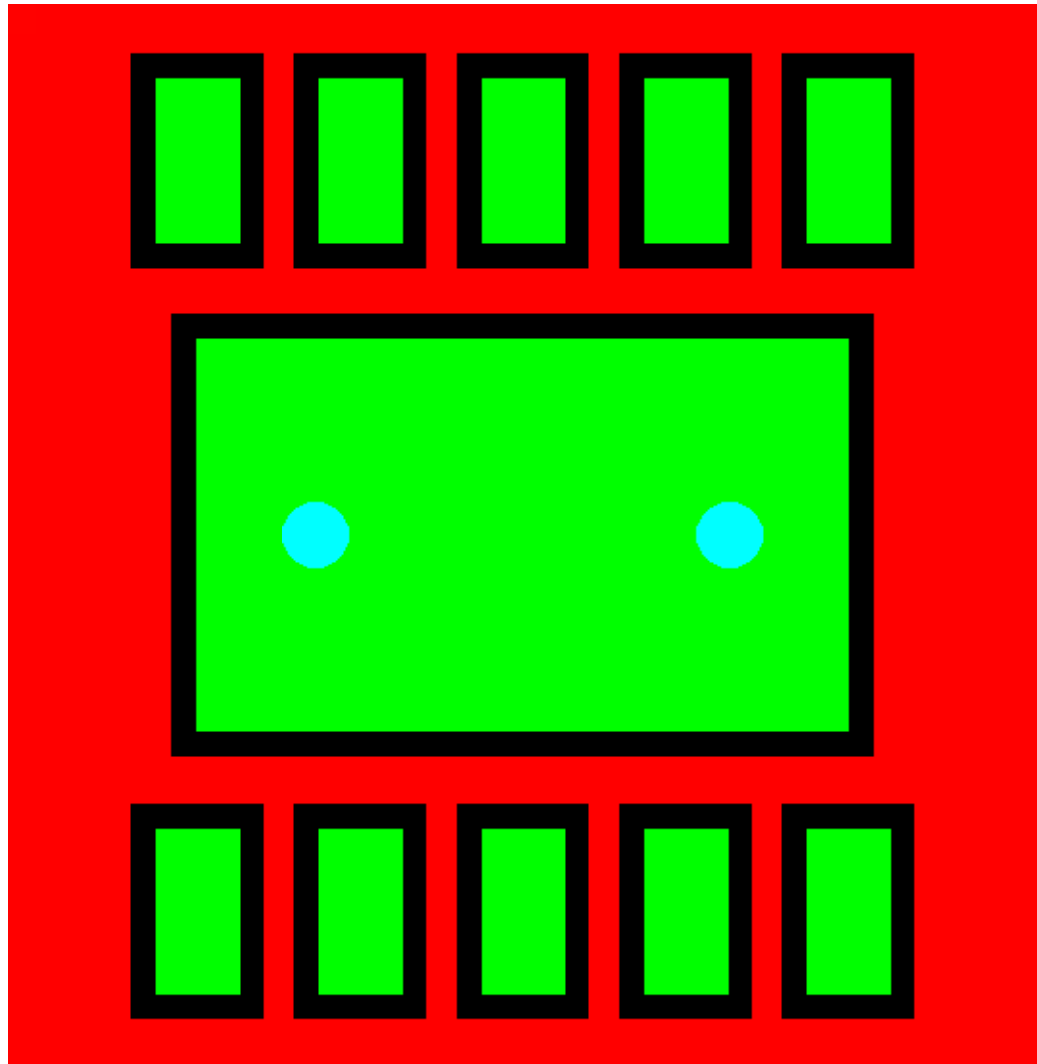
 = Exposed FR4

 = Mask over FR4

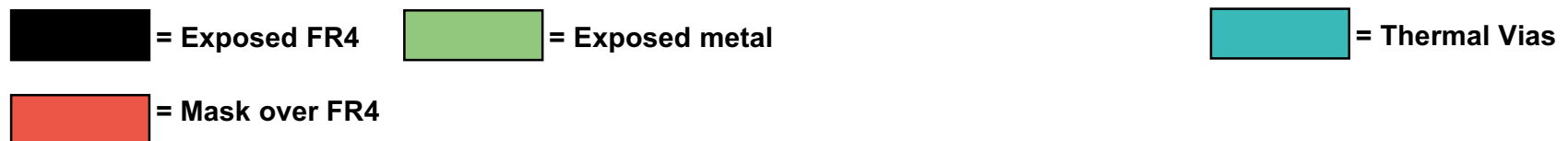


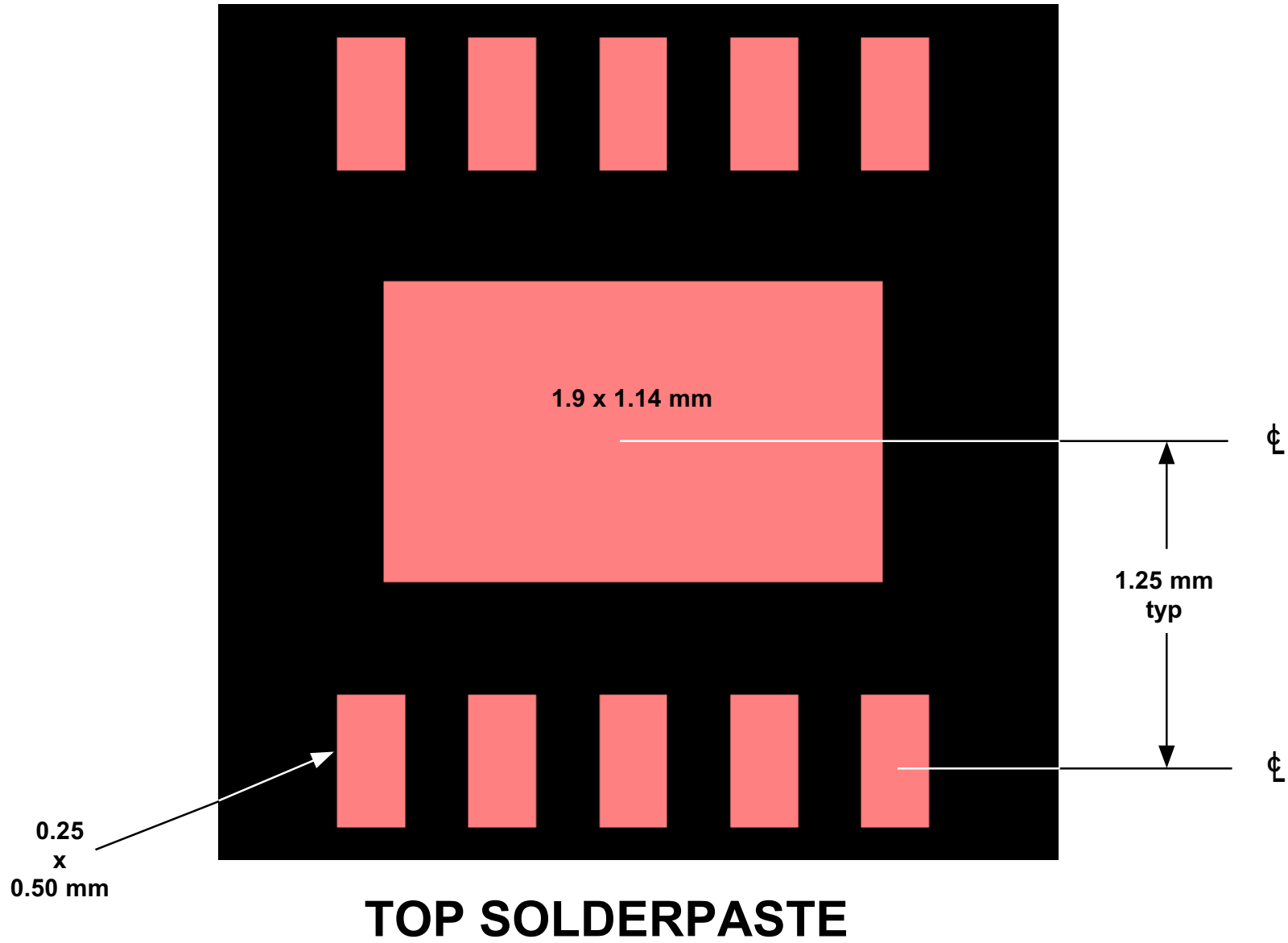
TOP ETCH + SOLDERMASK



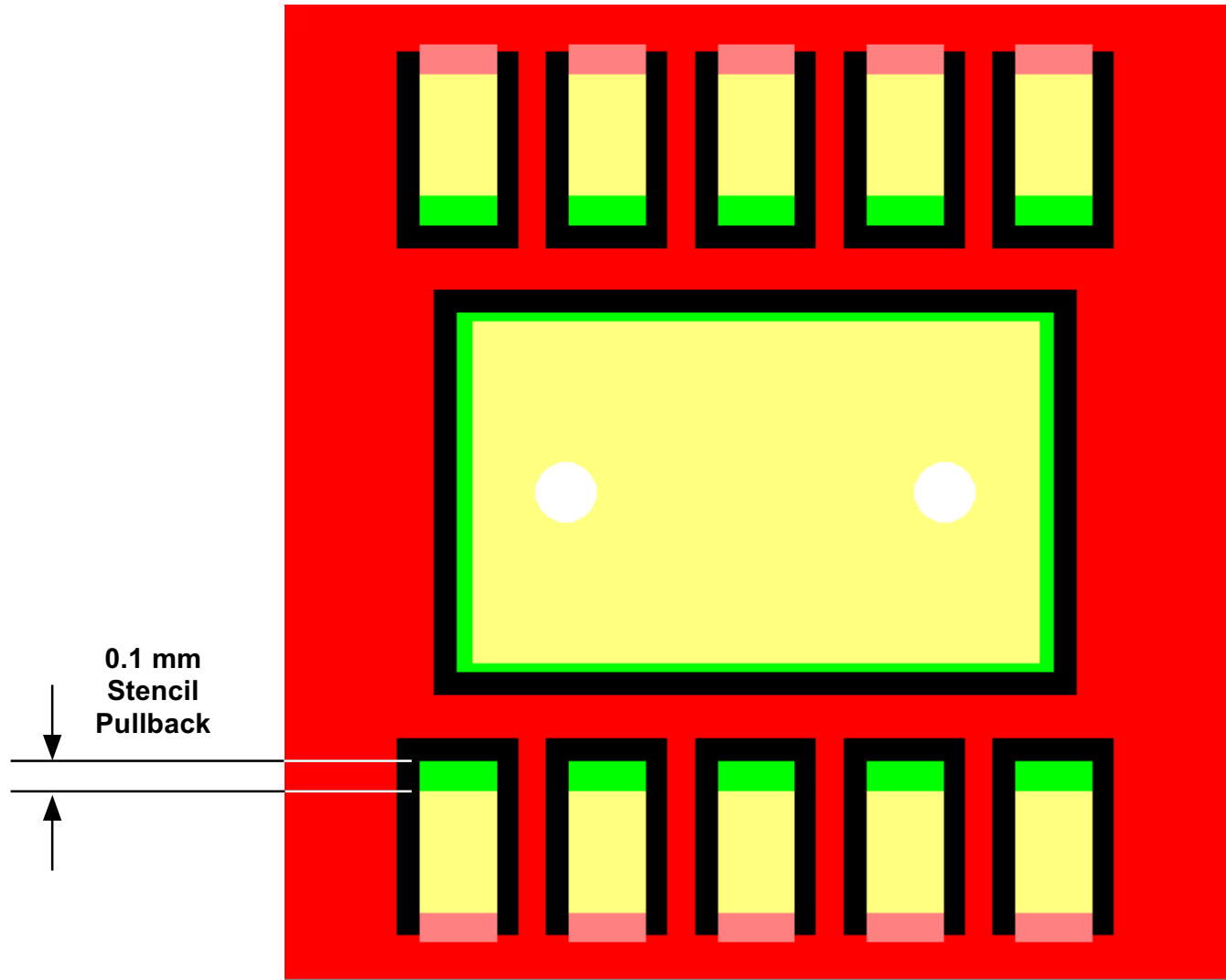


TOP ETCH + SOLDERMASK + THERMAL VIAS

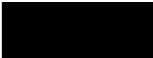


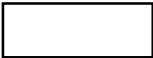






 = Paste



TOP ETCH + SOLDERMASK + SOLDERPASTE + THERMAL VIAS

- | | | | | | | | |
|---|-----------------|---|-----------------|---|------------------------------------|---|-------------------------------|
|  | = Exposed FR4 |  | = Exposed metal |  | = Paste over FR4
(0.1mm offset) |  | = Thermal Vias
under Paste |
|  | = Mask over FR4 | | |  | = Paste over
Metal | | |